



RECEIVED  
SEP 25 2003  
TC 1700

500.40269X00

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: HABA et al.

Serial No.: 09/888,642

Filed: June 26, 2001

For: ELECTRIC COPPER PLATING LIQUID AND PROCESS FOR  
MANUFACTURING SEMICONDUCTOR INTEGRATED

Art Unit: 1753

Examiner: E. Wong

#  
4/A  
10.11.  
10/2/03AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

September 22, 2003

Sir:

In response to the Office Action mailed August 20, 2003, please amend the  
above-identified application as listed in the following and as set forth on the following  
pages:

**Amendments to the Claims****Remarks** are included following the amendments.

10/08/2003 WHITCHEL 00000006 012135 09888642

01 FC:1201 84.00 DA